



**THE DATASHEET OF
SG1525AL-883B**

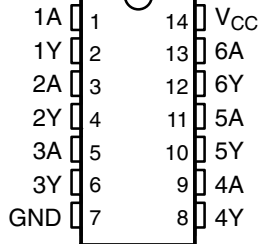


SN54AHC04, SN74AHC04 HEX INVERTERS

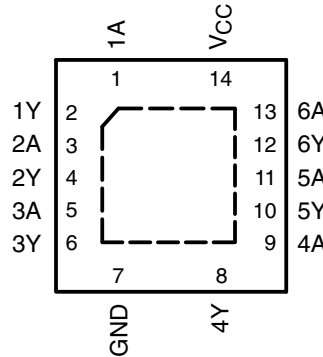
SCLS234K – OCTOBER 1995 – REVISED JULY 2003

- Operating Range 2-V to 5.5-V V_{CC}
- Unbuffered Outputs
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

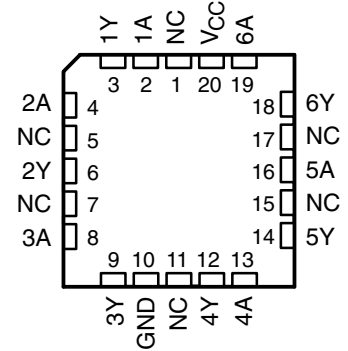
SN54AHC04 . . . J OR W PACKAGE
SN74AHC04 . . . D, DB, DGV, N, NS,
OR PW PACKAGE
(TOP VIEW)



SN74AHC04 . . . RGY PACKAGE
(TOP VIEW)



SN54AHC04 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

The 'AHC04 devices contain six independent inverters. These devices perform the Boolean function $Y = \bar{A}$. Internal circuitry consists of single-stage inverters that can be used in analog applications such as crystal oscillators.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Tape and reel	SN74AHC04RGYR	HD04
	PDIP – N	Tube	SN74AHC04N	SN74AHC04N
	SOIC – D	Tube	SN74AHC04D	AHC04
		Tape and reel	SN74AHC04DR	
	SOP – NS	Tape and reel	SN74AHC04NSR	AHC04
	SSOP – DB	Tape and reel	SN74AHC04DBR	HD04
	TSSOP – PW	Tube	SN74AHC04PW	HD04
Tape and reel		SN74AHC04PWR		
–55°C to 125°C	TVSOP – DGV	Tape and reel	SN74AHC04DGVR	HD04
	CDIP – J	Tube	SNJ54AHC04J	SNJ54AHC04J
	CFP – W	Tube	SNJ54AHC04W	SNJ54AHC04W
	LCCC – FK	Tube	SNJ54AHC04FK	SNJ54AHC04FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

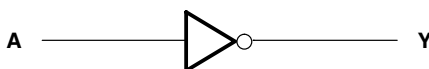
SN54AHC04, SN74AHC04 HEX INVERTERS

SCLS234K – OCTOBER 1995 – REVISED JULY 2003

FUNCTION TABLE
(each inverter)

INPUT A	OUTPUT Y
H	L
L	H

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input voltage range, V_I (see Note 1)	-0.5 V to 7 V
Output voltage range, V_O (see Note 1)	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	-20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	± 20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 25 mA
Continuous current through V_{CC} or GND	± 50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	86°C/W
(see Note 2): DB package	96°C/W
(see Note 2): DGV package	127°C/W
(see Note 2): N package	80°C/W
(see Note 2): NS package	76°C/W
(see Note 2): PW package	113°C/W
(see Note 3): RGY package	47°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.
 3. The package thermal impedance is calculated in accordance with JESD 51-5.

SN54AHC04, SN74AHC04 HEX INVERTERS

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recommended operating conditions (see Note 4)

		SN54AHC04		SN74AHC04		UNIT
		MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	2	5.5	2	5.5	V
V _{IH}	High-level input voltage	V _{CC} = 2 V		1.7		V
		V _{CC} = 3 V		2.4		
		V _{CC} = 5.5 V		4.4		
V _{IL}	Low-level input voltage	V _{CC} = 2 V		0.3		V
		V _{CC} = 3 V		0.6		
		V _{CC} = 5.5 V		1.1		
V _I	Input voltage	0	5.5	0	5.5	V
V _O	Output voltage	0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 2 V		-50		μA
		V _{CC} = 3.3 V ± 0.3 V		-4		
		V _{CC} = 5 V ± 0.5 V		-8		
I _{OL}	Low-level output current	V _{CC} = 2 V		50		μA
		V _{CC} = 3.3 V ± 0.3 V		4		
		V _{CC} = 5 V ± 0.5 V		8		
T _A	Operating free-air temperature	-55	125	-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AHC04		SN74AHC04		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 μA	2 V	1.8	2	1.8	1.8	V			
		3 V	2.7	3	2.7	2.7				
		4.5 V	4	4.5	4	4				
	I _{OH} = -4 mA	3 V	2.58		2.48	2.48				
	I _{OH} = -8 mA	4.5 V	3.94		3.8	3.8				
V _{OL}	I _{OL} = 50 μA	2 V			0.2	0.2	0.2	V		
		3 V			0.3	0.3	0.3			
		4.5 V			0.5	0.5	0.5			
	I _{OL} = 4 mA	3 V			0.36	0.5	0.44			
	I _{OL} = 8 mA	4.5 V			0.36	0.5	0.44			
I _I	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1	±1*	±1	μA		
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			2	20	20	μA		
C _i	V _I = V _{CC} or GND	5 V		2	10		10	pF		

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.



SN54AHC04, SN74AHC04 HEX INVERTERS

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**switching characteristics over recommended operating free-air temperature range,
V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			SN54AHC04		SN74AHC04		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	C _L = 15 pF	5*	7.1*	1*	8.5*	1	8.5	ns	
t _{PHL}				5*	7.1*	1*	8.5*	1	8.5		
t _{PLH}	A	Y	C _L = 50 pF	7.5	10.6	1	12	1	12	ns	
t _{PHL}				7.5	10.6	1	12	1	12		

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

**switching characteristics over recommended operating free-air temperature range,
V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T _A = 25°C			SN54AHC04		SN74AHC04		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	C _L = 15 pF	3.5*	5.5*	1*	6*	1	6.5	ns	
t _{PHL}				3.5*	5.5*	1*	6*	1	6.5		
t _{PLH}	A	Y	C _L = 50 pF	5	7	1	8	1	8	ns	
t _{PHL}				5	7	1	8	1	8		

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 5)

PARAMETER		SN74AHC04			UNIT
		MIN	TYP	MAX	
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.5		V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.5		V
V _{OH(V)}	Quiet output, minimum dynamic V _{OH}		4.3		V
V _{IH(D)}	High-level dynamic input voltage	4			V
V _{IL(D)}	Low-level dynamic input voltage			1	V

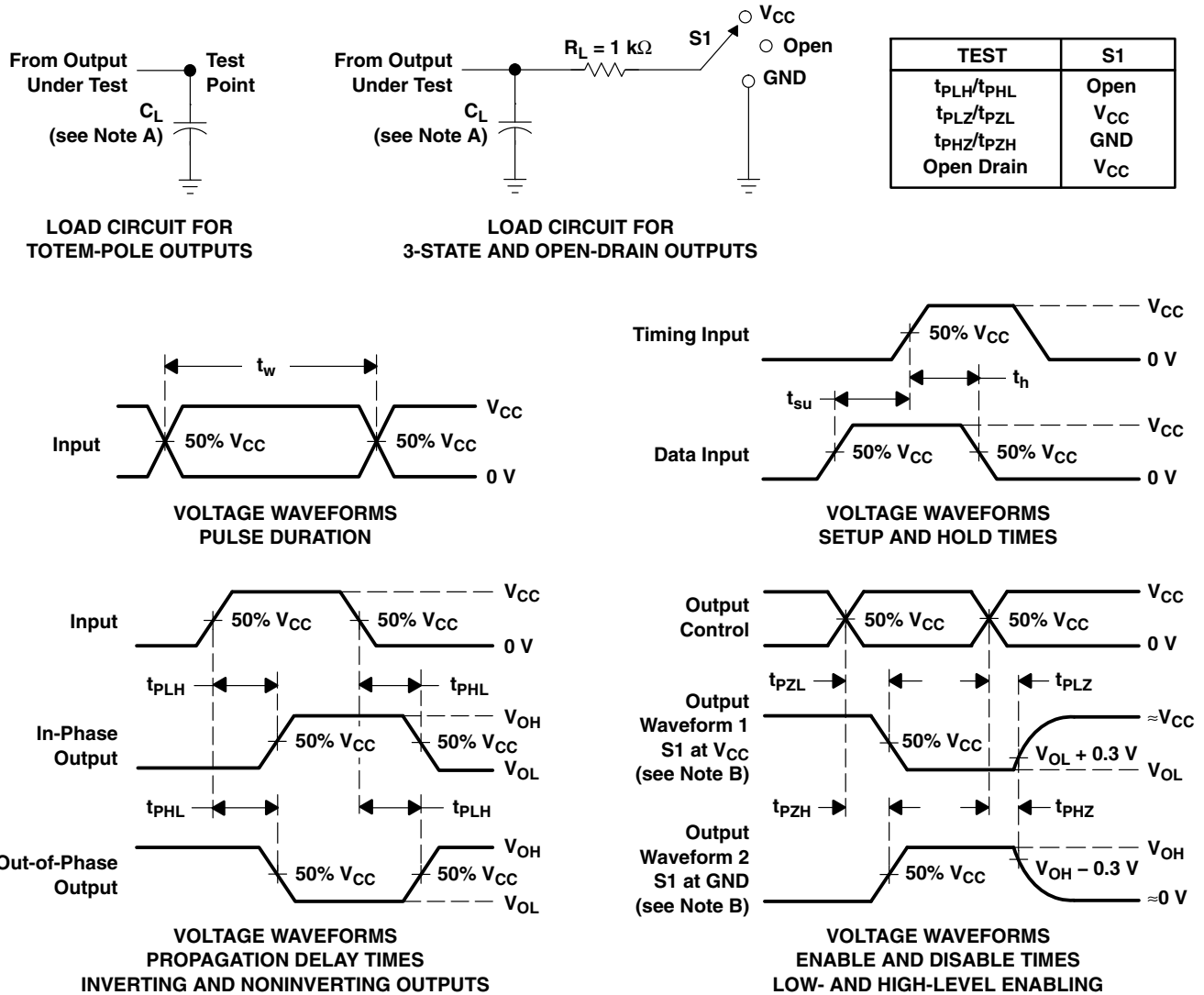
NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance	No load, f = 1 MHz	7.3	pF



PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_r \leq 3$ ns, $t_f \leq 3$ ns.
 D. The outputs are measured one at a time with one input transition per measurement.
 E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9680301QDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9680301QD A SNJ54AHCU04W	Samples
SN74AHCU04DBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HD04	Samples
SN74AHCU04DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCU04	Samples
SN74AHCU04N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74AHCU04N	Samples
SN74AHCU04NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AHCU04	Samples
SN74AHCU04PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HD04	Samples
SN74AHCU04PWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HD04	Samples
SNJ54AHCU04W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9680301QD A SNJ54AHCU04W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54AHC04, SN74AHC04 :

- Catalog : [SN74AHC04](#)

- Automotive : [SN74AHC04-Q1](#), [SN74AHC04-Q1](#)

- Enhanced Product : [SN74AHC04-EP](#), [SN74AHC04-EP](#)

- Military : [SN54AHC04](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

- Enhanced Product - Supports Defense, Aerospace and Medical Applications

- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHC04DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74AHC04DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AHC04NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AHC04PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCU04DBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74AHCU04DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74AHCU04NSR	SO	NS	14	2000	356.0	356.0	35.0
SN74AHCU04PWR	TSSOP	PW	14	2000	356.0	356.0	35.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-9680301QDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74AHC04N	N	PDIP	14	25	506	13.97	11230	4.32
SN74AHC04N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54AHC04W	W	CFP	14	25	506.98	26.16	6220	NA

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

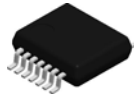
W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14

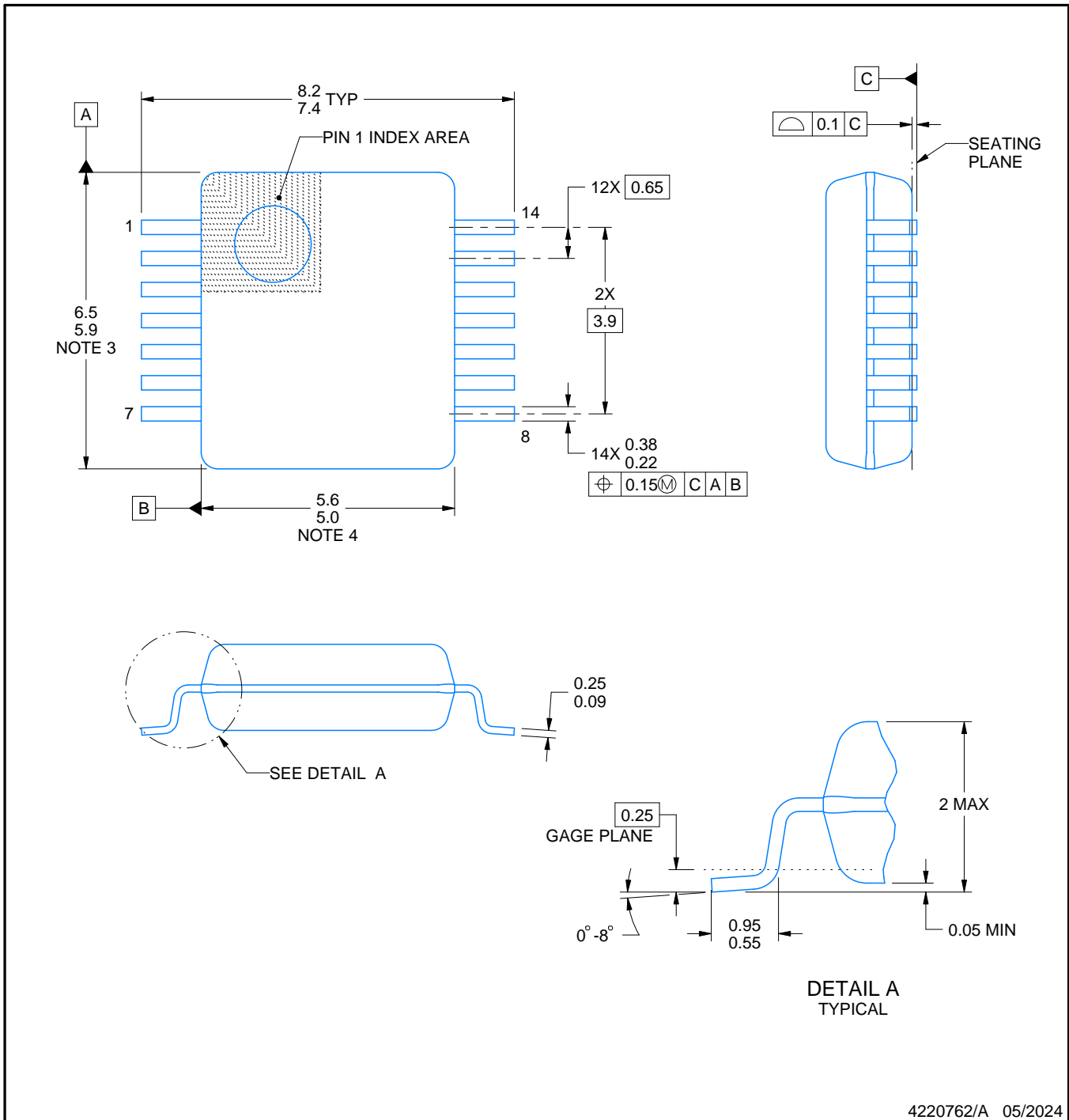
DB0014A



PACKAGE OUTLINE

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

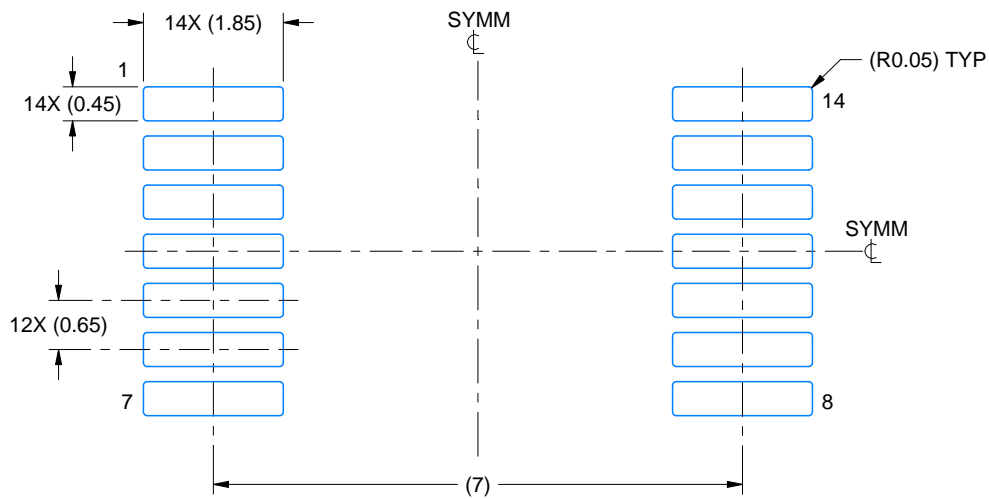
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

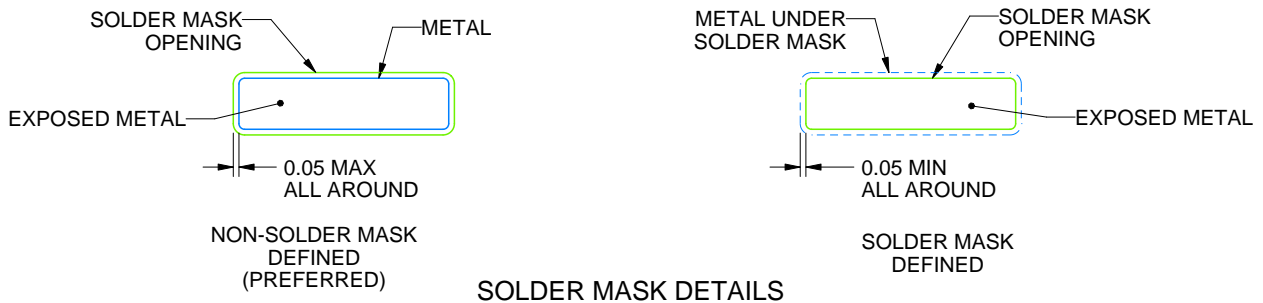
DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



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NOTES: (continued)

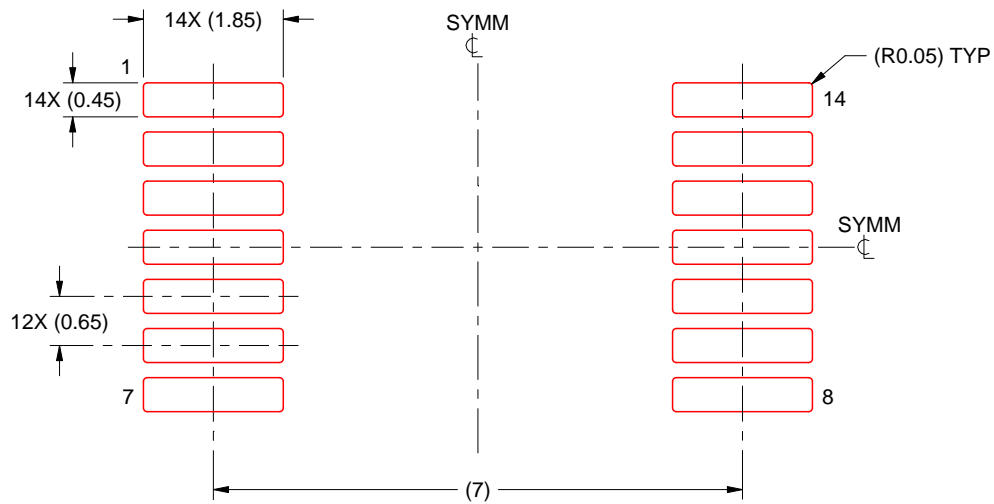
- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220762/A 05/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE





- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



4040064-3/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

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